MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

QFN32, 7x7
CASE 560AA
ISSUE A

DATE 23 SEP 2015

PIN 1 CORNER

EXPOSED DIE ATTACH PAD
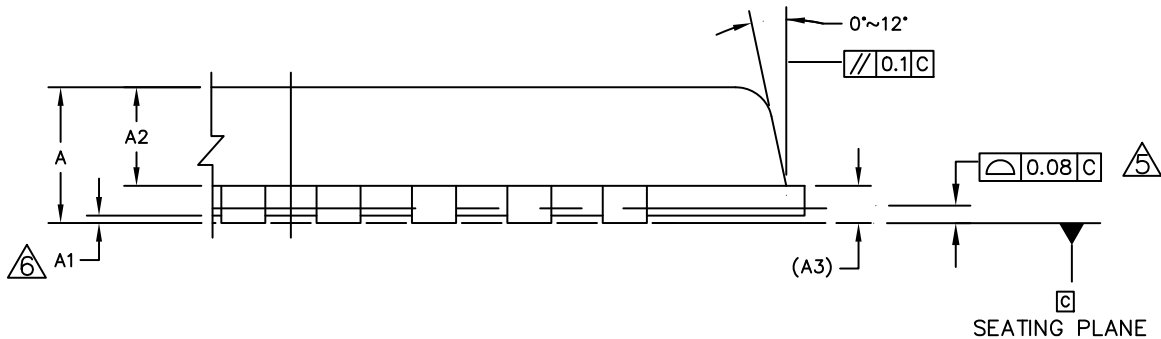
R0.2
(PIN1 I.D.)

(0.1016)

(0.2)

32X L

32X b
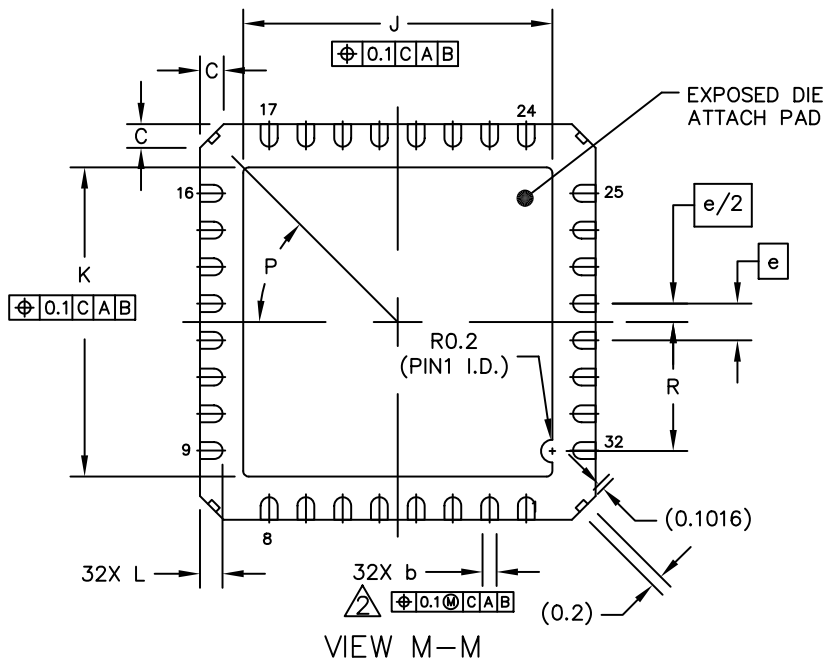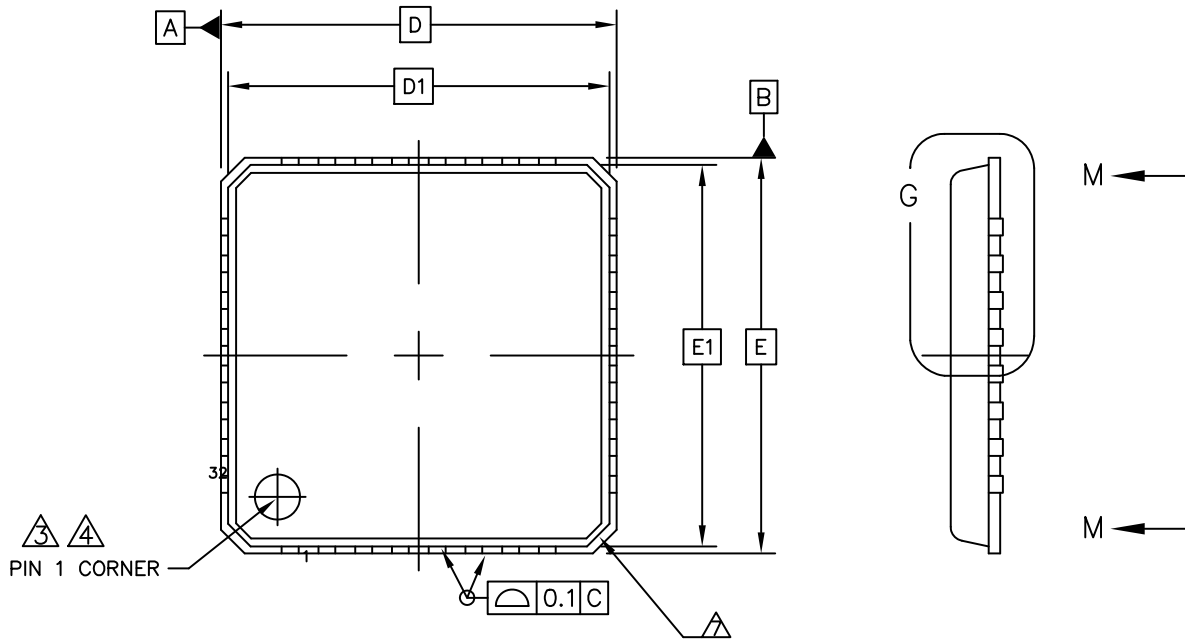
VIEW M—M

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DESCRIPTION:	**QFN32, 7X7**		**PAGE 1 OF 2**

0°~12°

// 0.1 C

0.08 C ⚠5

A2

A

A1 ⚠6

(A3)

C
SEATING PLANE

DETAIL G
VIEW ROTATED 90° CLOCKWISE

DIM	MIN	NOM	MAX	NOTES
A	0.8		0.9	1. DIE THICKNESS ALLLOWABLE IS 0.305mm MAXIMUM (.012 INCHES MAXIMUM)
A1	0	0.02	0.05	
A2	0.576	0.615	0.654	⚠2 DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.2 AND 0.25mm FROM TERMINAL TIP.
A3	0.203 REF.			
b	0.25	0.3	0.35	⚠3 THE PIN #1 IDENTIFIER MUST BE PLACED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
C	0.24	0.42	0.6	
D	7 BSC			
D1	6.75 BSC			⚠4 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
E	7 BSC			
E1	6.75 BSC			⚠5 APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING.
e	0.65 BSC			
J	5.37	5.47	5.57	⚠6 APPLIED ONLY TO TERMINALS.
K	5.37	5.47	5.57	
L	0.35	0.4	0.45	⚠7 EXACT SHAPE OF EACH CORNER IS OPTIONAL.
P	45° REF			
R	2.185		2.385	

UNIT	DIMENSION AND TOLERANCES	REFERENCE DOCUMENT
MM	ASME_Y14.5M	JEDEC—MO—220_REV.F

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